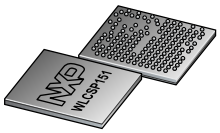
SOT2152-1

WLCSP151 wafer level chip-size package, 151 terminals, 0.3 mm pitch, 5.165 mm x 4.68 mm x 0.455 mm body (backside coating included)

29 November 2024 Package information



1 Package summary

Terminal position code	P (perpendicular)
Package type descriptive code	WLCSP151
Package style descriptive code	WLCSP (wafer level chip-size package)
Package body material type	S (silicon)
Mounting method type	S (surface mount)
Issue date	04-05-2023
Manufacturer package code	98ASA01782D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	5.135	5.165	5.195	mm
package width	4.65	4.68	4.71	mm
package height	0.425	0.455	0.485	mm
nominal pitch	-	0.3	-	mm

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2 Package outline

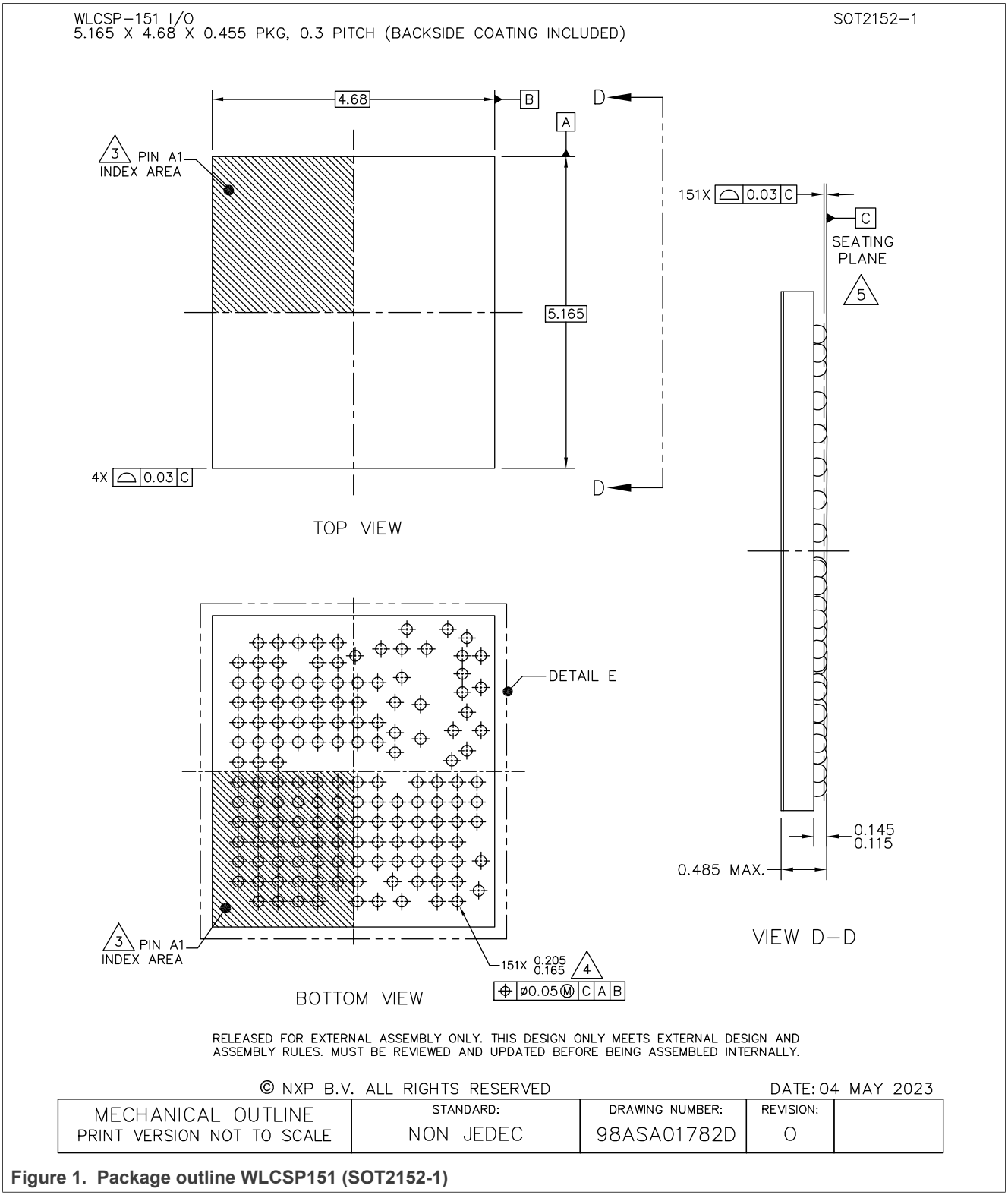

Figure 1. Package outline WLCSP151 (SOT2152-1)

WLCSP151 wafer level chip-size package, 151 terminals, 0.3 mm pitch, 5.165 mm x 4.68 mm x 0.455 mm body (backside coating included)

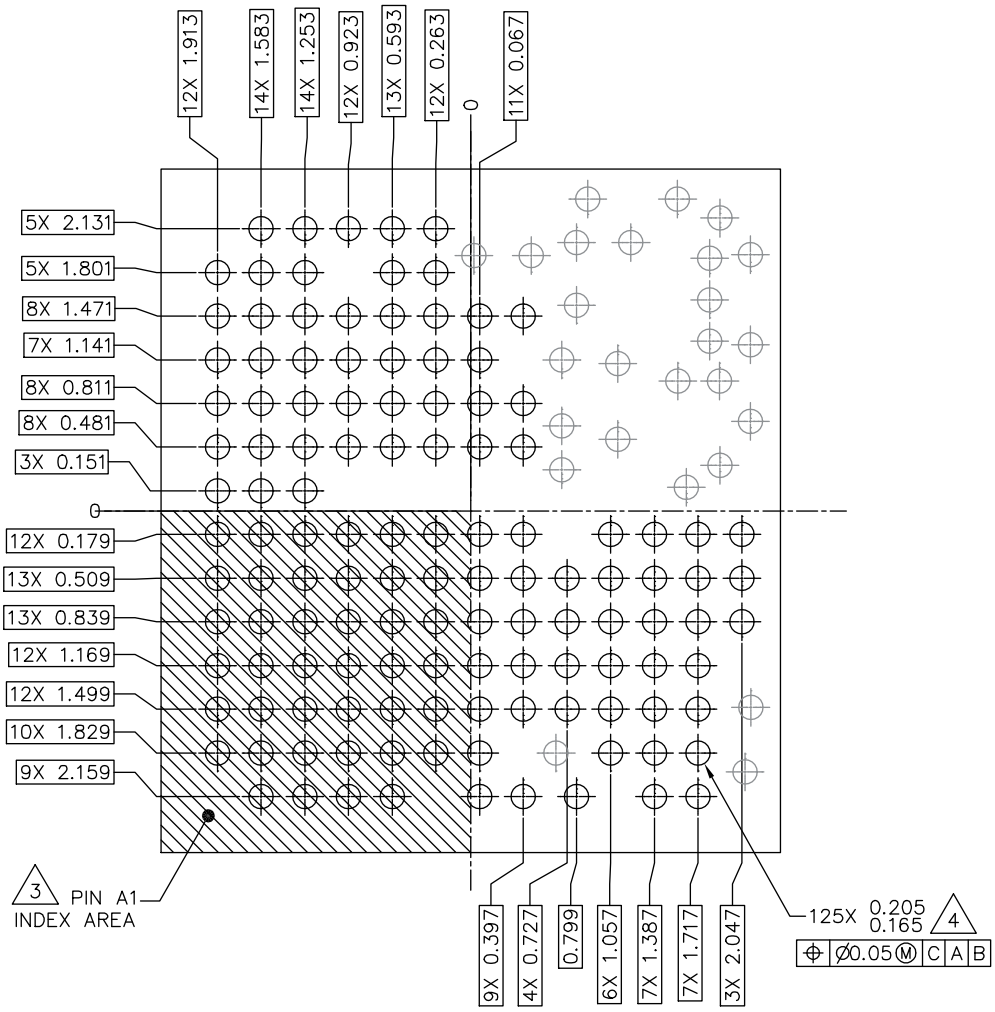

Figure 2. Package outline detail E of WLCSP151 (SOT2152-1)

3 Soldering

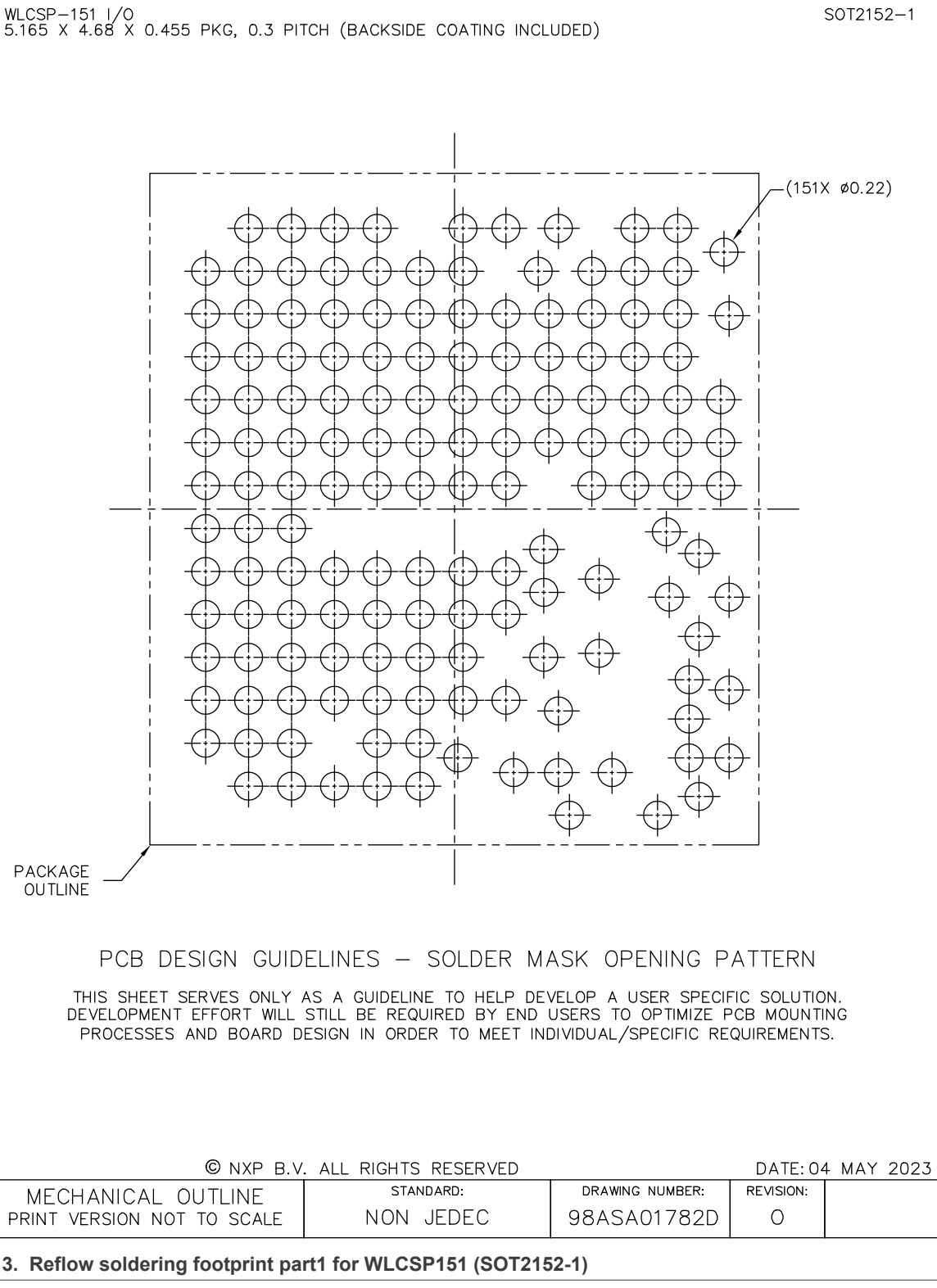

Figure 3. Reflow soldering footprint part1 for WLCSP151 (SOT2152-1)

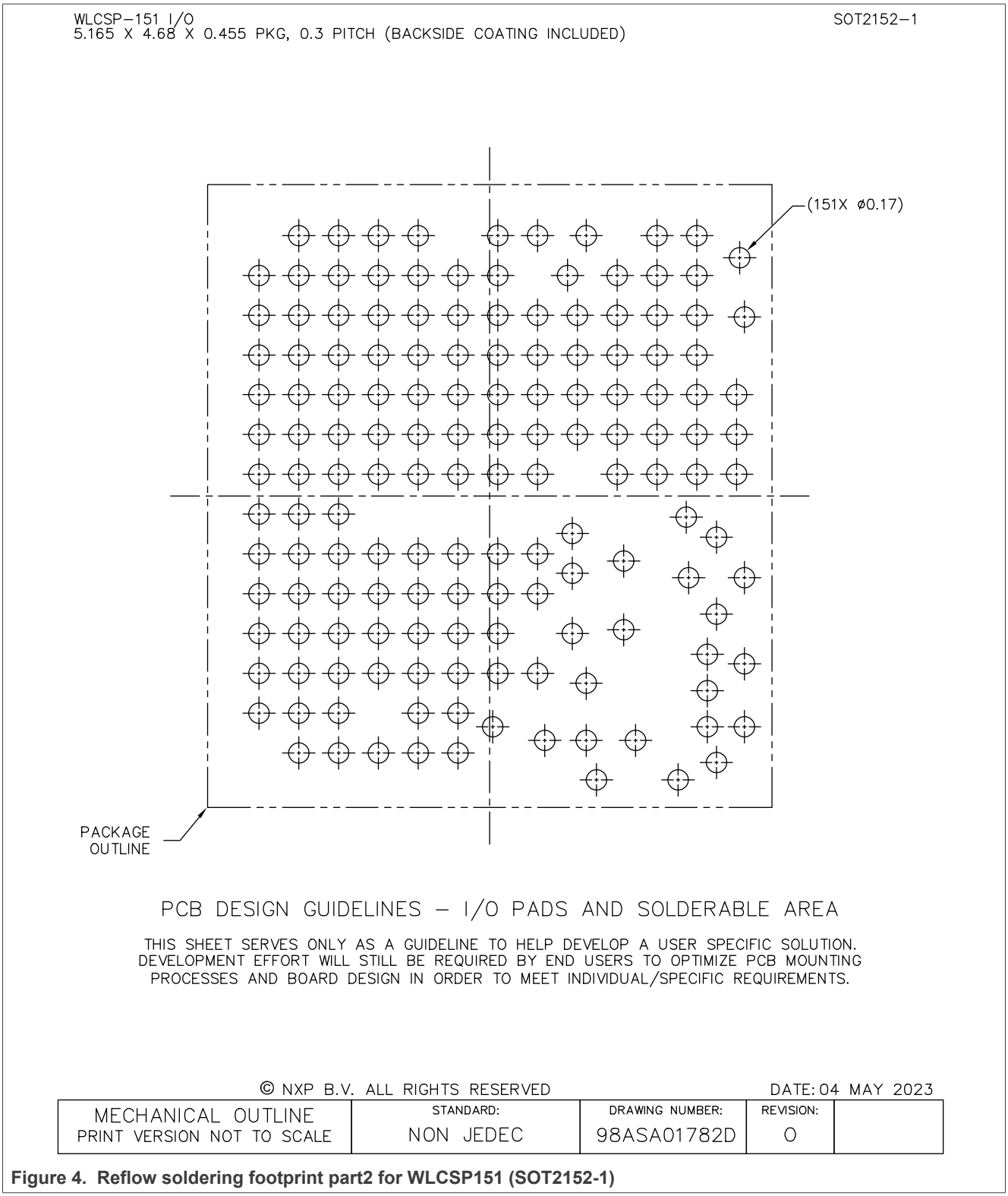

Figure 4. Reflow soldering footprint part2 for WLCSP151 (SOT2152-1)

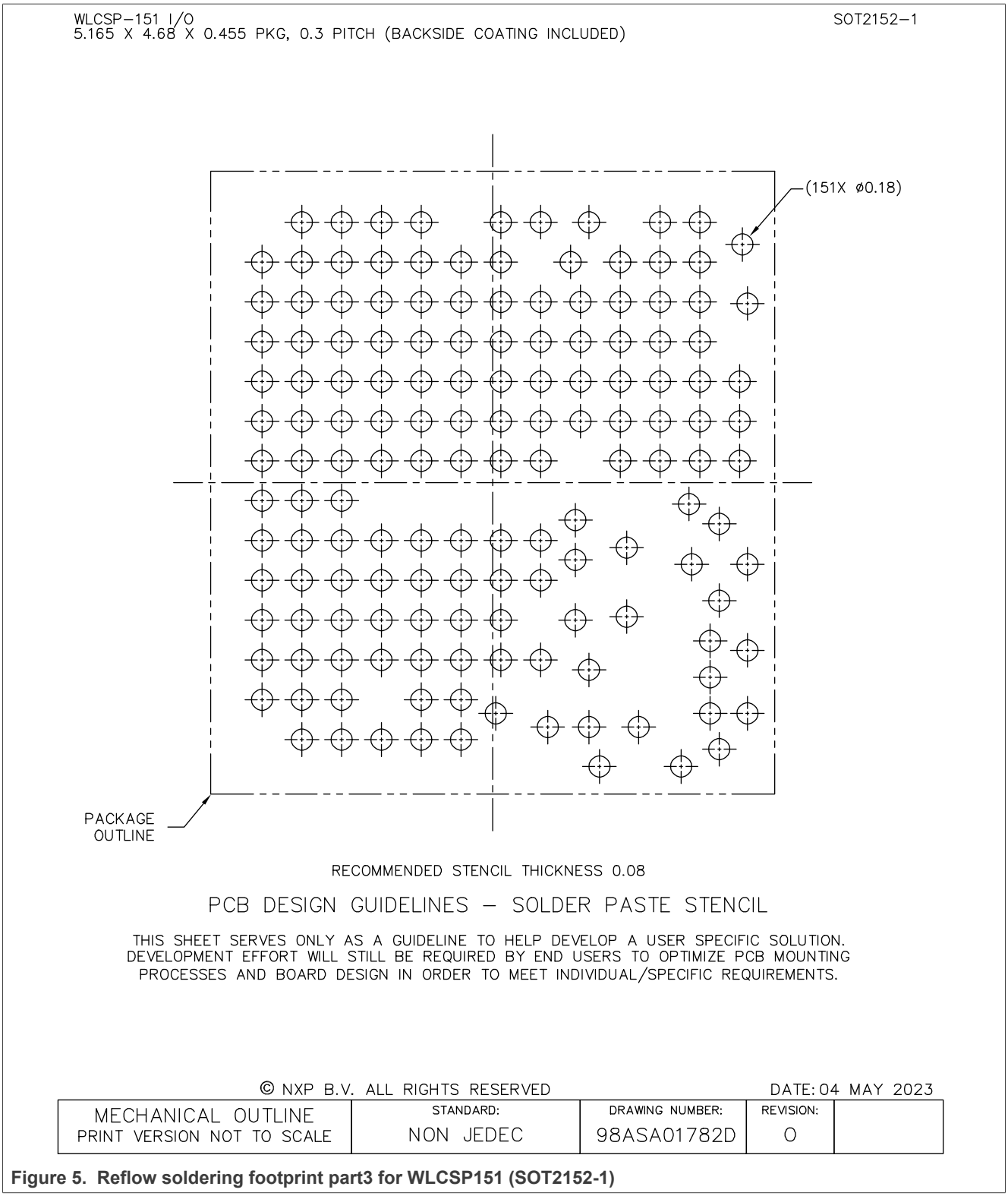

Figure 5. Reflow soldering footprint part3 for WLCSP151 (SOT2152-1)

WLCSP151 wafer level chip-size package, 151 terminals, 0.3 mm pitch, 5.165 mm x 4.68 mm x 0.455 mm body (backside coating included)

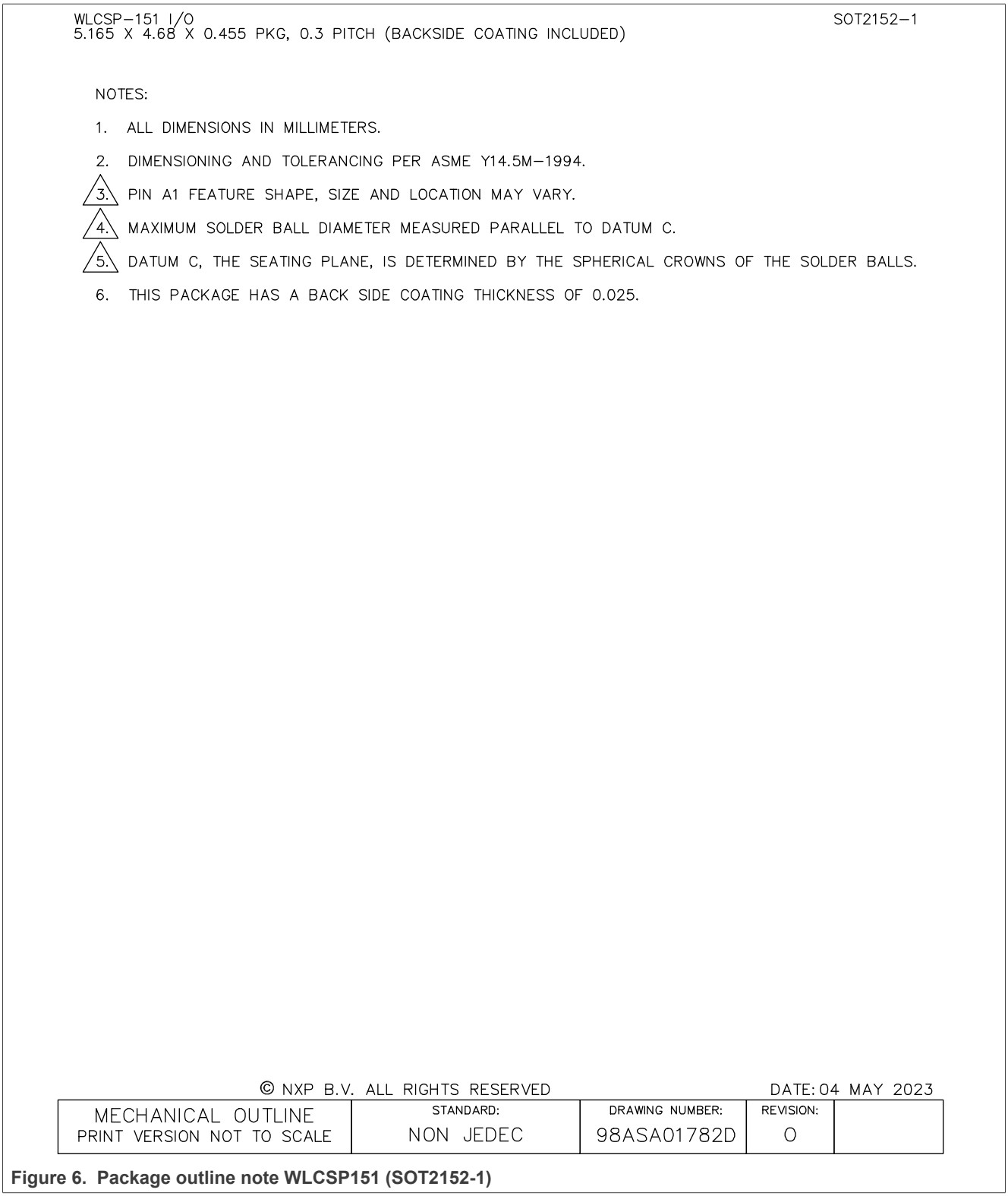

Figure 6. Package outline note WLCSP151 (SOT2152-1)

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WLCSP151 wafer level chip-size package, 151 terminals, 0.3 mm pitch, 5.165 mm x 4.68 mm x 0.455 mm body (backside coating included)

Contents

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